Application Number		SEARCH			
DS Flag Cle	arance for Ap	plication 1079072	3		
	Content	Mailroom Date	Entry Number	IDS Review	Reviewer
;	M844	11-16-2005	23	V	11-22-2005 10:31:50 Ihinton
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## **Refine Search**

## Search Results -

Terms	Documents	
L26 and (via\$ near8 wafer)	11	

US Pre-Grant Publication Full-Text Database

Database:

US Patents Full-Text Database
US OCR Full-Text Database
EPO Abstracts Database
JPO Abstracts Database
Derwent World Patents Index
IBM Technical Disclosure Bulletins

Search:

.27	Ā	Refine Search
	$\checkmark$	Reille Search







## **Search History**

DATE: Wednesday, March 15, 2006 Printable Copy Create Case

Set Name side by side	Query	<u>Hit</u> Count	Set Name result set
DB=I	PGPB; PLUR=YES; OP=OR		
<u>L27</u>	L26 and (via\$ near8 wafer)	11	<u>L27</u>
<u>L26</u>	(micro near5 (device or chip or die) near15 wafer) and ((cavity near5 (wafer)) and cavity near5 (cap or encapsulant or cover))	61	<u>L26</u>
DB=0	USPT; PLUR=YES; OP=OR		
<u>L25</u>	(micro near5 (device or chip or die) near15 wafer) and ((cavity near5 (wafer)) and cavity near5 (cap or encapsulant or cover))	34	<u>L25</u>
<u>L24</u>	L12 and ((cavity near5 (wafer)) and cavity near5 (cap or encapsulant or cover))	3	<u>L24</u>
<u>L23</u>	L12 and ((cavity near5 (substrate)) and cavity near5 (cap or encapsulant or cover))	4	<u>L23</u>
<u>L22</u>	L12 and ((cavity near5 (substrate)) and 9cavity near5 (cap or encapsulant or cover))	0	<u>L22</u>
<u>L21</u>	5668033 and ("51")	15	<u>L21</u>

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DB =	PGPB; PLUR=YES; OP=OR		
<u>L20</u>	L19 and "peripheral metal"	1	<u>L20</u>
<u>L19</u>	L18 and perimeter	1	<u>L19</u>
<u>L18</u>	20050073040	1	<u>L18</u>
DB=	USPT; PLUR=YES; OP=OR		
<u>L17</u>	(bump near5 pad\$) near7 packaging	122	<u>L17</u>
<u>L16</u>	L15 and "338"	1	<u>L16</u>
<u>L15</u>	6114191 and pads	4	<u>L15</u>
<u>L14</u>	L13 and (external near6 pad\$)	15	<u>L14</u>
<u>L13</u>	L12 and (cap or encapsul\$6)	123	<u>L13</u>
<u>L12</u>	L11 and (via\$ near8 wafer)	639	<u>L12</u>
<u>L11</u>	L10 and (pads near6 surface near8 wafer)	2718	<u>L11</u>
<u>L10</u>	((device or chip or die)) near15 wafer	57123	<u>L10</u>
<u>L9</u>	L8 and (via\$ near8 wafer)	6	<u>L9</u>
<u>L8</u>	L7 and ((pad\$ near6 surface) near10 wafer)	32	<u>L8</u>
<u>L7</u>	(micro near5 (device or chip or die)) near15 wafer	. 616	<u>L7</u>
<u>L6</u>	L5 and (via\$ near8 wafer)	6	<u>L6</u>
<u>L5</u>	L4 and (pads near6 surface near8 wafer)	26	<u>L5</u>
<u>L4</u>	(micro near5 (device or chip or die)) near8 wafer	536	<u>L4</u>
<u>L3</u>	6271081	6	<u>L3</u>
<u>L2</u>	6777263	4	<u>L2</u>
L1	5144412	12	L1

END OF SEARCH HISTORY